


# MATERIAL DECLARATION SHEET

Package Type	PTVS1-066C-TH			
Product Line	Semiconductor products			
Compliance Date	22 <sup>th</sup> May 2019			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.06142	Bisphenol Copolymer	25036-25-3	60	3.4109	5.6849
				Alumina Trihydrate	21645-51-2	15	0.8527	
				Fused Silica	60676-86-0	20	1.137	
				Hydrated Iron Oxide	20344-49-4	1.5	0.0853	
				Titanium Dioxide	13463-67-7	1.5	0.0853	
				Melamine Cyanurate	37640-57-6	1.5	0.0853	
				Amine Adduct	Trade Secret	0.5	0.0284	
2	Electrodes	Copper Alloy	0.7006	Copper	7440-50-8	99.1	64.2615	64.8451
				Silver	7440-22-4	0.4	0.2594	
				Misc, not to declare	-	0.5	0.3242	
3	Terminations	Copper Alloy	0.214	Copper	7440-50-8	99.5	19.7081	19.8071
				Misc, not to declare	-	0.5	0.099	
4	Chip	Silicon	0.0538	Silicon	7440-21-3	85.34	4.2495	4.9795
				Aluminum	7429-90-5	5.13	0.2555	
				Nickel	7440-02-0	9.09	0.4526	
				Gold	7440-57-5	0.44	0.0219	
5	Die Attach	Solder	0.0146	Lead	7439-92-1	92.5	1.25	1.3514
				Tin	7440-31-5	5	0.0676	
				Silver	7440-22-4	2.5	0.0338	
6	Die Coating	Silicone	0.036	Polysiloxane	63148-62-9	22.11	0.7367	3.332
				Chromium Sesquioxide	1308-38-9	5.67	0.1889	
				Fumed Silica	112945-52-5	11.11	0.3702	
				Filler	Trade Secret	61.11	2.0362	
		Total Weight	1.08042					

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\* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)